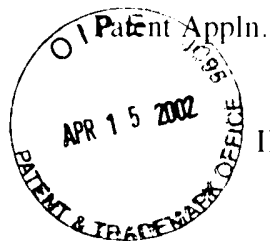


Case No.: AMKOR-019RCE



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Erasmo Perez et al.

Group No.: 2814

Serial No.: 09/436,158

Examiner: Nathan W. Ha

Filed: 11/09/1999

For: SEMICONDUCTOR PACKAGE
WITH EXPOSED DIE PAD AND
BODY-LOCKING LEADFRAME

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON D C 20231

Dear Sir/Madam:

Prior to the examination of the present Request for Continued Examination (RCE) Application, please amend the application as follows:

In the Claims:

13. (Twice Amended) A semiconductor package, comprising:

a metal lead frame, including a plurality of elongate leads arrayed around a central region thereof, each lead having an outer end portion extending away from the central region,

between the outer and inner end portions, the middle portion of the lead frame having

having a lower surface which defines a land.